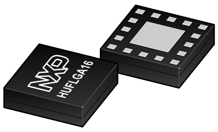


SOT2174-1

HUFLGA16, thermal enhanced very very thin finepitch land grid array package, 0.4 mm pitch, 2 mm x 2 mm x 0.54 mm body

2 June 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-01-2022
Manufacturer package code	98ASA01878D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	2	-	mm
package width	-	2	-	mm
seated height	-	0.54	0.582	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	16	-	

2 Package outline

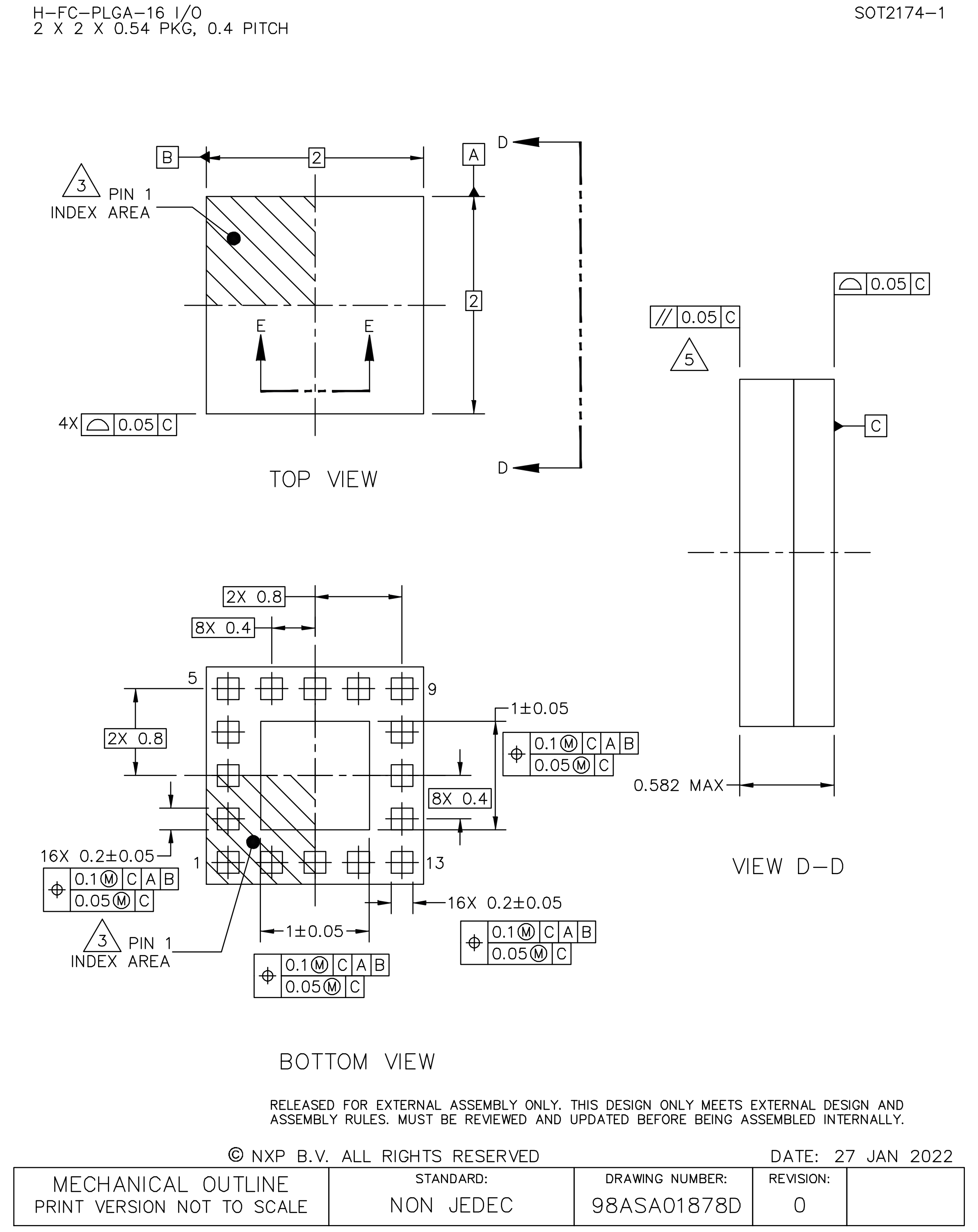
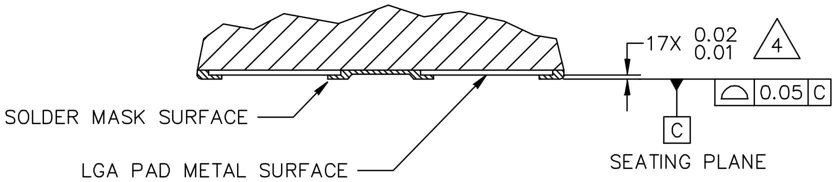


Figure 1. Package outline HUFLGA16 (SOT2174-1)

H-FC-PLGA-16 I/O
2 X 2 X 0.54 PKG, 0.4 PITCH

SOT2174-1



SECTION E-E

VIEW ROTATED 90° CW

DATE: 27 JAN 2022

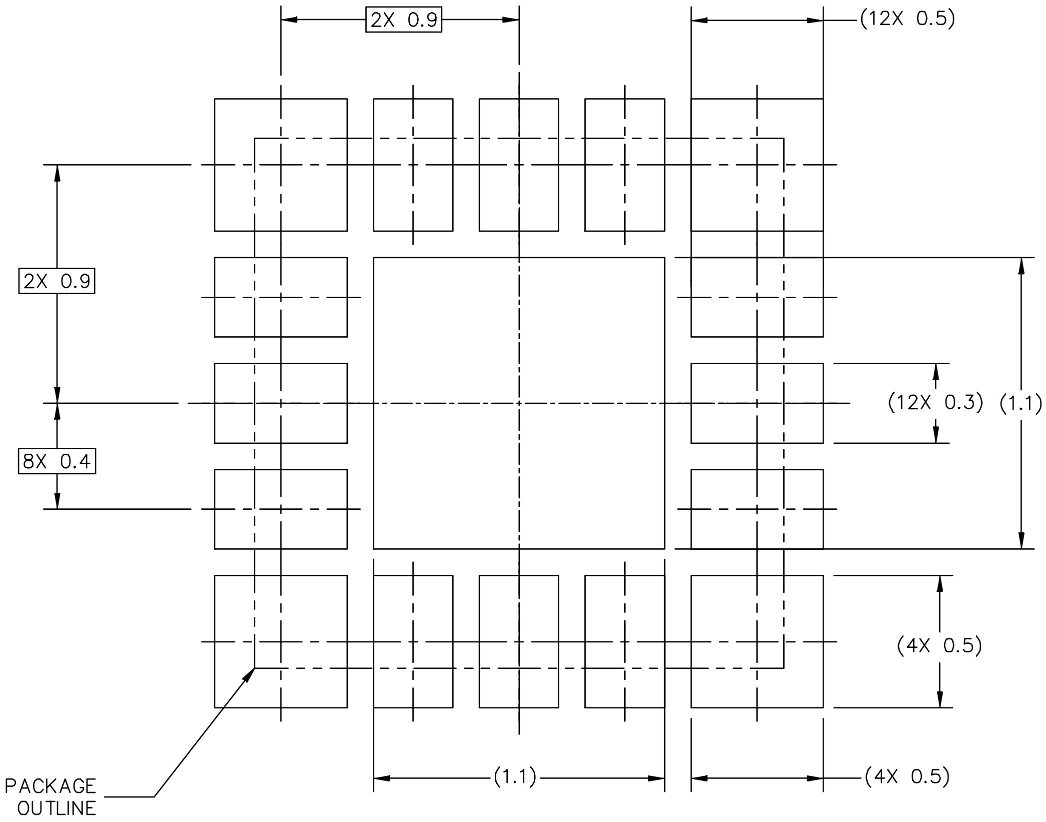
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01878D	REVISION: 0	

Figure 2. Package outline detail E-E of HUFLGA16 (SOT2174-1)

3 Soldering

H-FC-PLGA-16 I/O
2 X 2 X 0.54 PKG, 0.4 PITCH

SOT2174-1



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

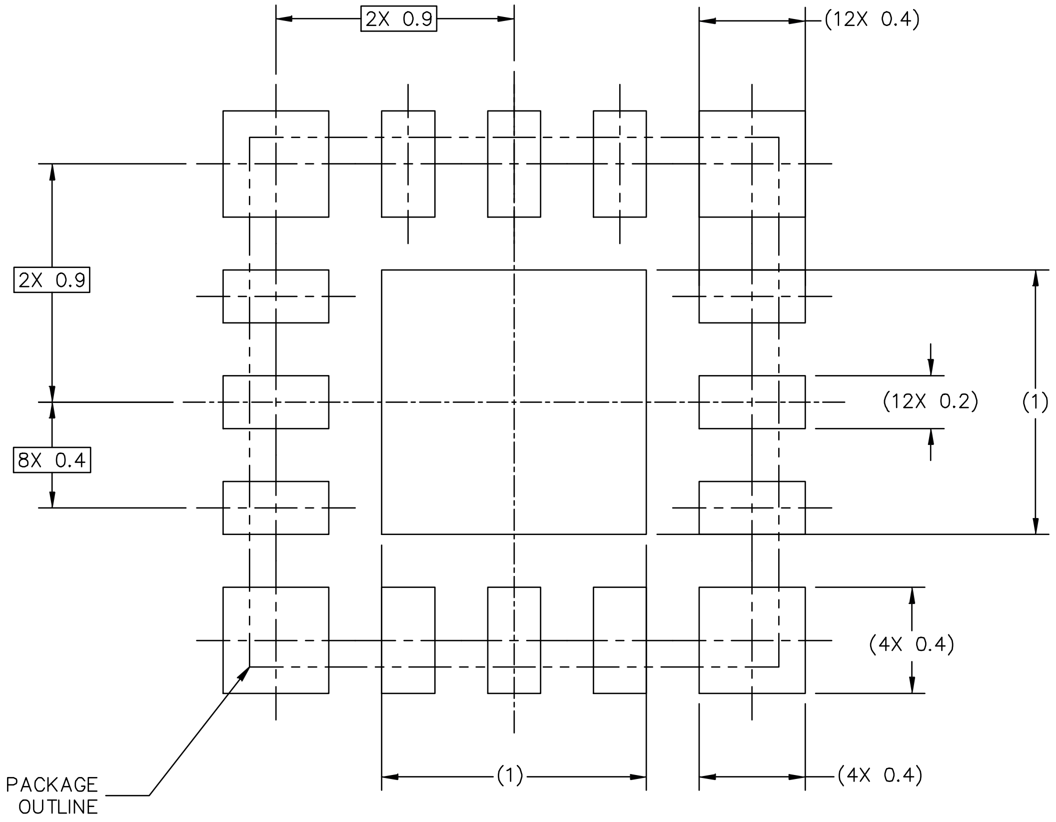
DATE: 27 JAN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01878D	REVISION: 0	

Figure 3. Reflow soldering footprint part1 for HUFLGA16 (SOT2174-1)

H-FC-PLGA-16 I/O
2 X 2 X 0.54 PKG, 0.4 PITCH

SOT2174-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 27 JAN 2022

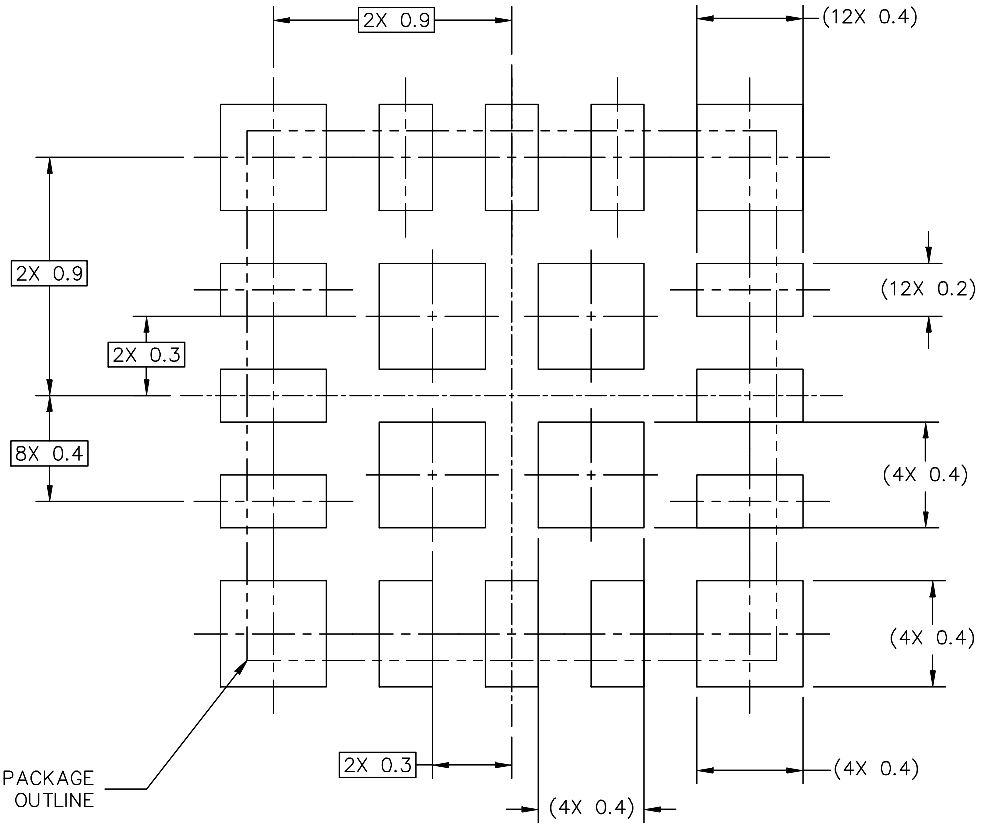
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01878D	REVISION: 0	

Figure 4. Reflow soldering footprint part2 for HUFLGA16 (SOT2174-1)

HUFLGA16, thermal enhanced very very thin finepitch land grid array package, 0.4 mm pitch, 2 mm x 2 mm x 0.54 mm body

H-FC-PLGA-16 I/O
2 X 2 X 0.54 PKG, 0.4 PITCH

SOT2174-1



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

DATE: 27 JAN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01878D	REVISION: 0	

Figure 5. Reflow soldering footprint part3 for HUFLGA16 (SOT2174-1)

H-FC-PLGA-16 I/O
2 X 2 X 0.54 PKG, 0.4 PITCH

SOT2174-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE

DATE: 27 JAN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01878D	REVISION: 0	

Figure 6. Package outline note HUFLGA16 (SOT2174-1)

4 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors’ aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 2 June 2022